1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
P_{IN}	Input Power RF_{IN}			20	dBm
V_{ESD}	ESD ratings MIL STD883C (HBM: C = 100 pF, R = 1.5 k Ω , air discharge)	2000			V
	ESD ratings charge device model (JESD22-C101-C)	500			
	ESD ratings machine model (MM: C = 200 pF, R = 25 Ω , L = 500 nH)	500			
T_{OP}	Operating temperature	-40		+105	°C

Table 2. Electrical characteristics (T_{amb} = 25 °C)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
Z_{OUT}	Nominal differential output impedance		conjugate match to: – nRF51822-QFAA/QFAB – nRF51422-QFAA/QFAB		Ω
Z_{IN}	Nominal input impedance		50		Ω
F	Frequency range (bandwidth)	2400		2540	
I_L	Insertion loss in bandwidth		1.35	1.46	dB
R_L	Return loss in bandwidth	16.5	17	17.5	dB
ϕimb	Phase imbalance	4.5	5	5.5	°
Aimb	Amplitude imbalance	0.15	0.2	0.25	dB
2f0	2nd harmonic filtering		-15	-14	dB
3f0	3rd harmonic filtering		-42	-41	dB

1.1 Simulations results (T_{amb} = 25 °C)

Figure 2. Insertion loss in band

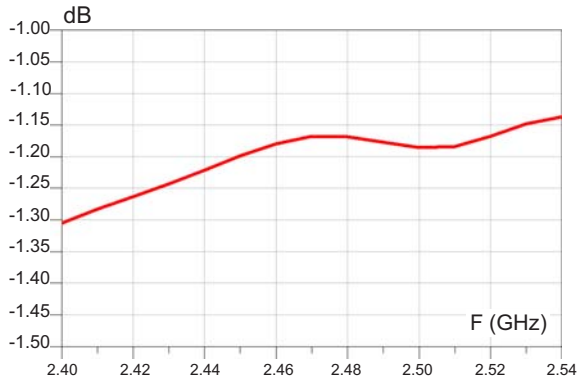


Figure 3. Differential transmission

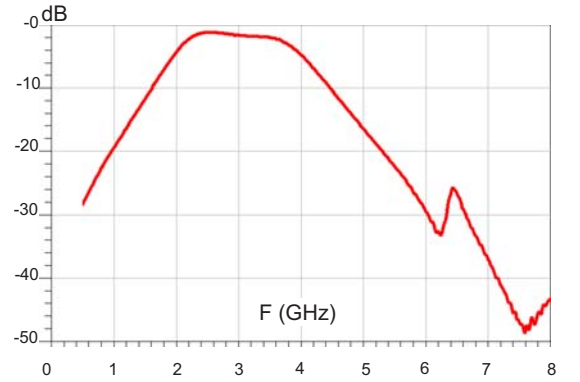


Figure 4. Return loss on SE port

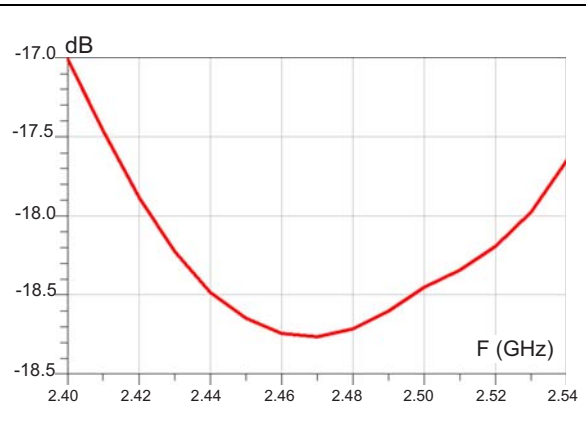


Figure 5. Amplitude imbalance

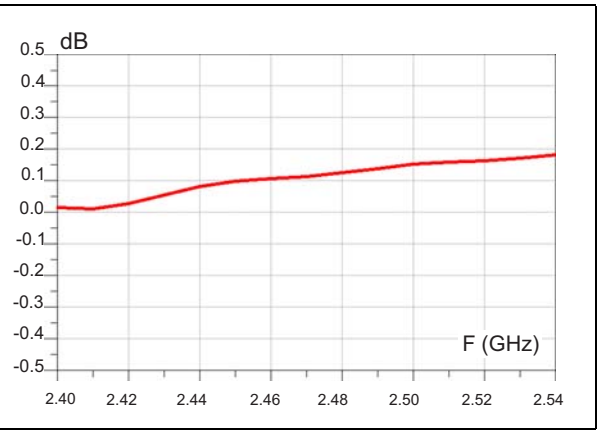


Figure 6. Phase imbalance

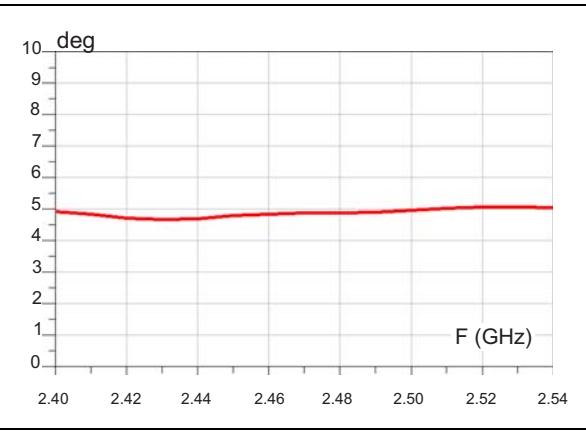


Figure 7. H2 attenuation

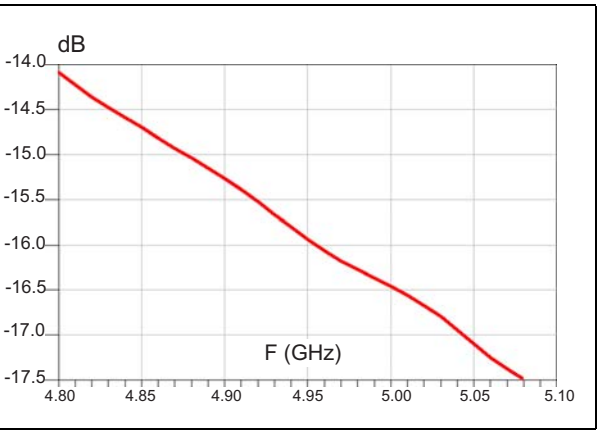


Figure 8. Attenuation in H3

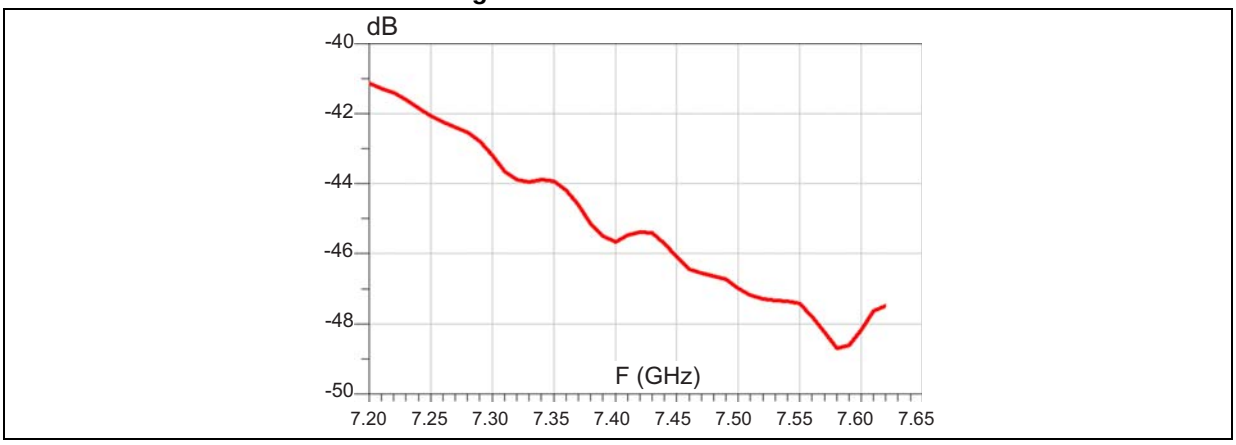


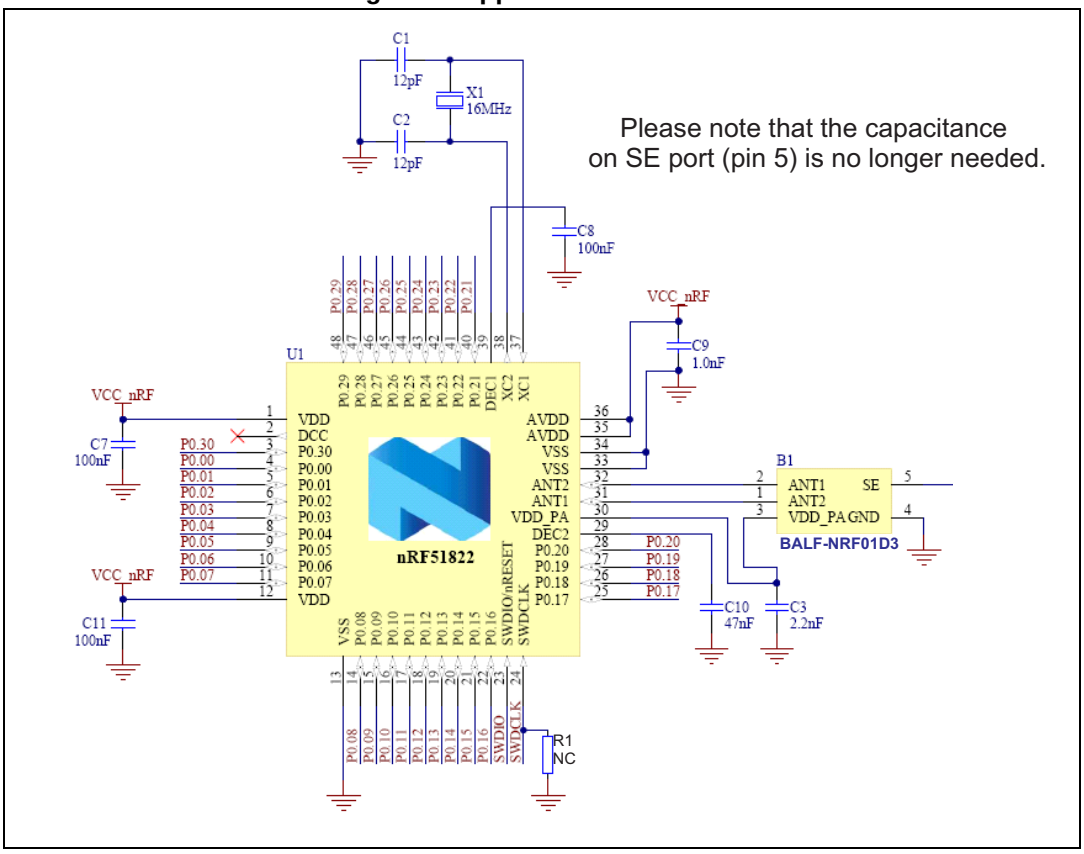
Table 3. Compatibility matrix (nRF51422)

nRF51422 IC revision	Packet/variant	Build code
2	QFAA	DAA
		Ex0
	QFAB	A00

Table 4. Compatibility matrix (nRF51822)

nRF51822 IC revision	Packet/variant	Build code
2	QFAA	FA0
		GC0
		Gx0
	QFAB	Bx0

Figure 9. Application schematic



2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Figure 10. Package dimensions (top and side view)

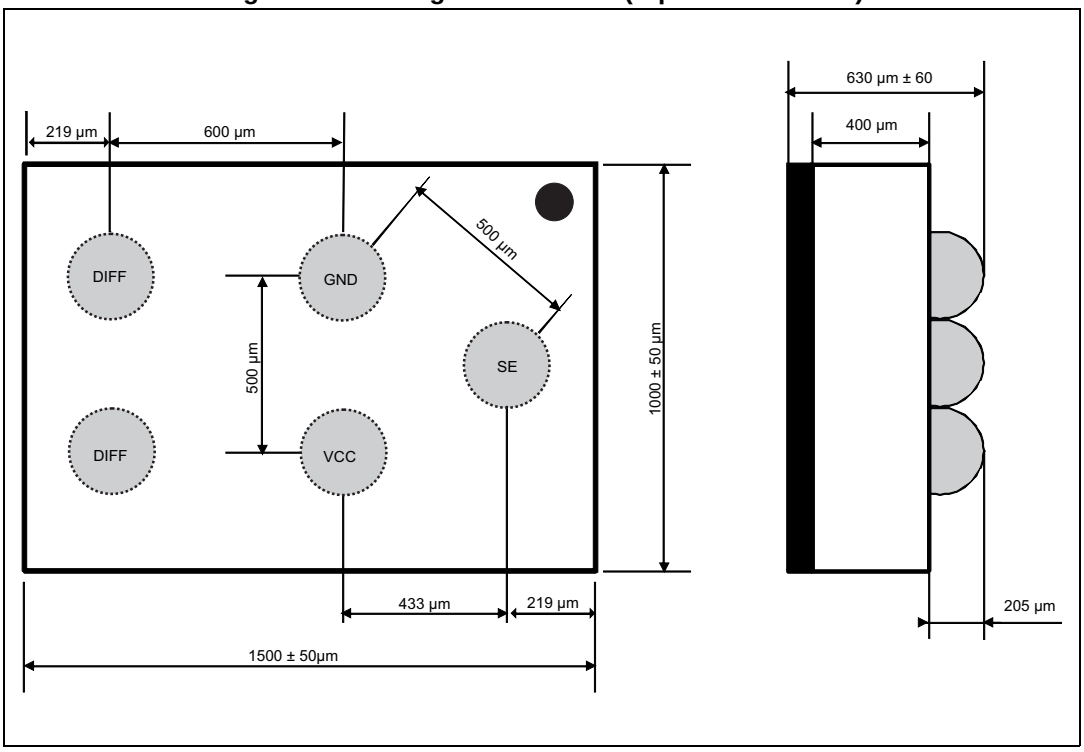


Figure 11. PCB layout recommendation

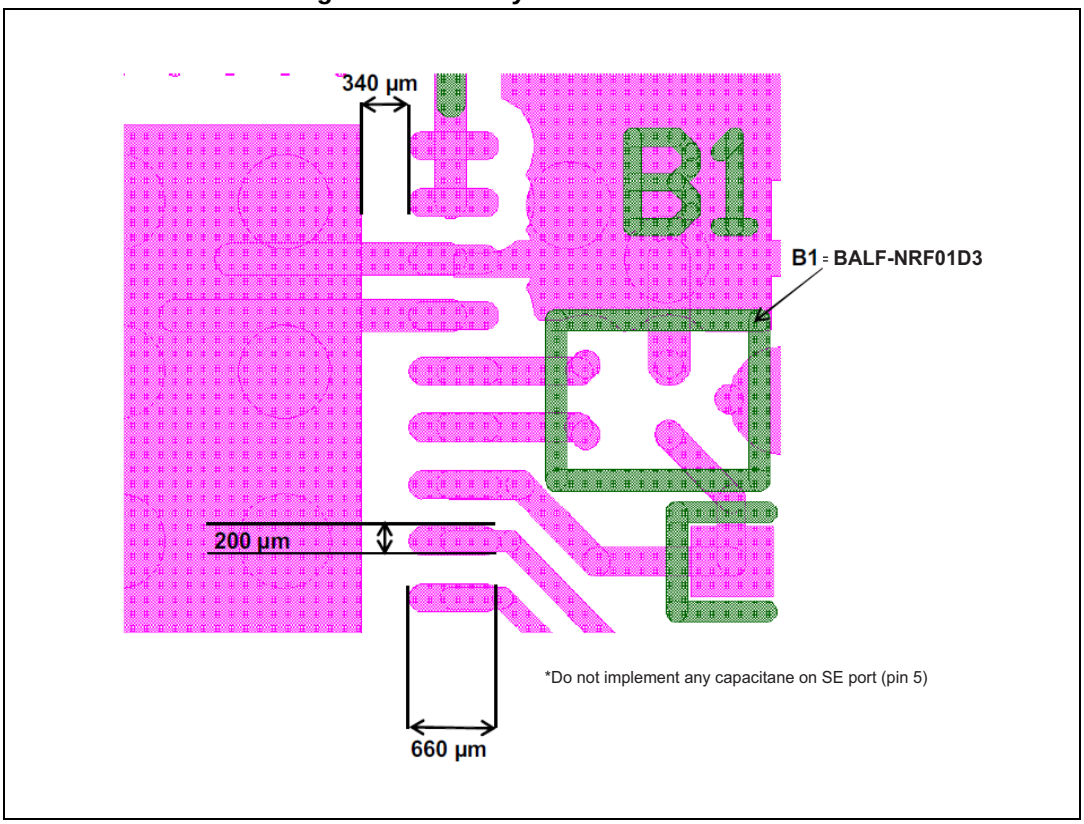


Figure 12. BALF-NRF01D3 position

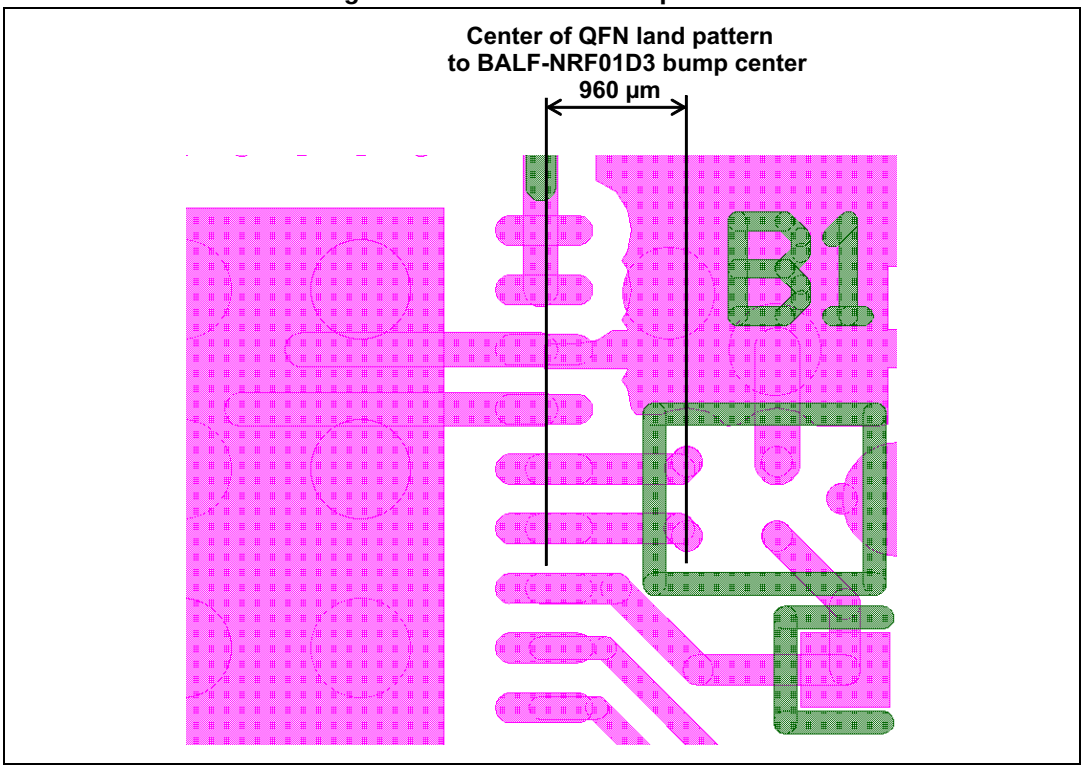


Figure 13. Marking

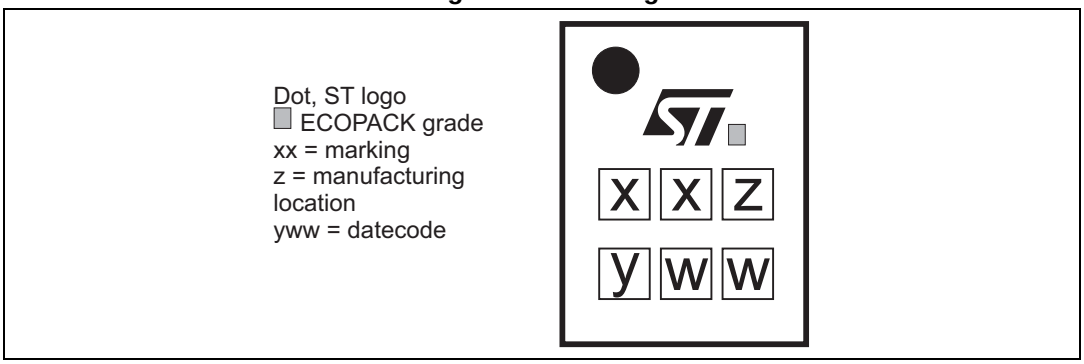
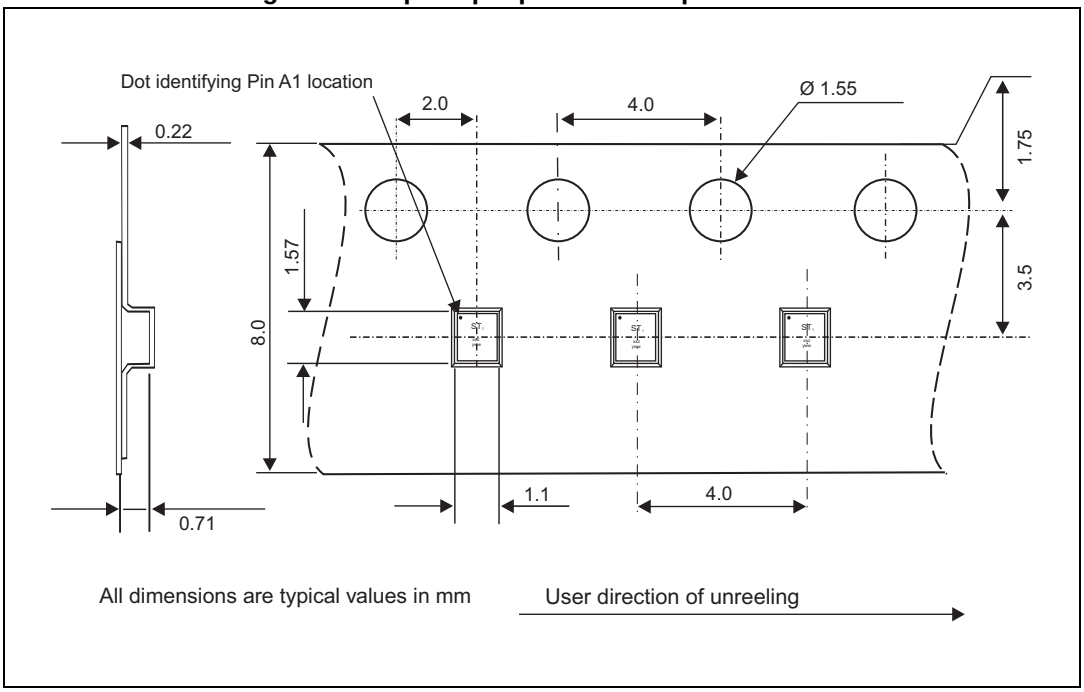


Figure 14. Flip-Chip tape and reel specifications



Note: More information is available in the STMicroelectronics Application note: AN2348 Flip-Chip: "Package description and recommendations for use"

Figure 15. Footprint - 3 mils stencil -non solder mask defined

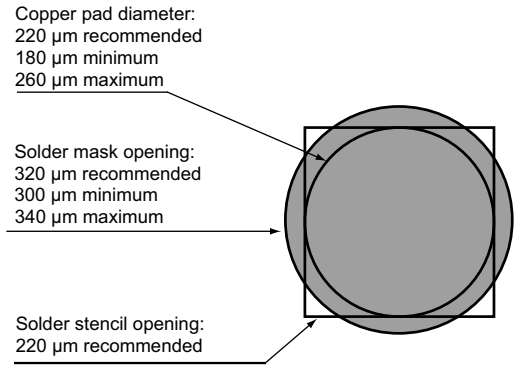


Figure 16. Footprint - 3 mils stencil - solder mask defined

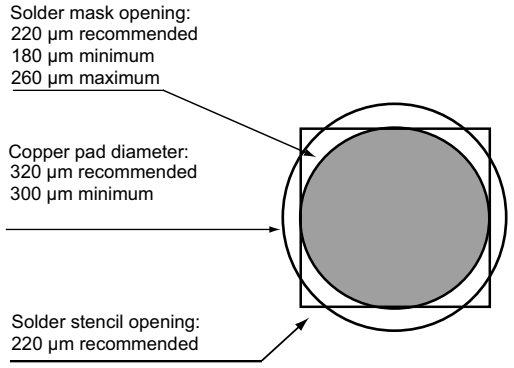


Figure 17. Footprint - 5 mils stencil -non solder mask defined

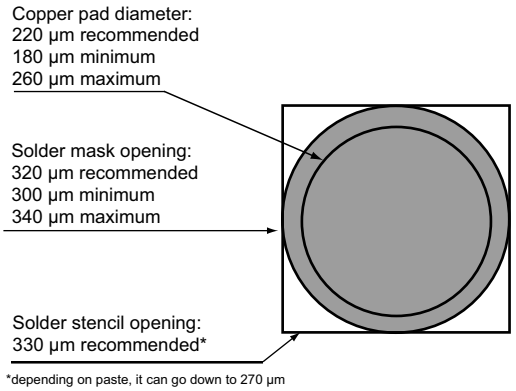
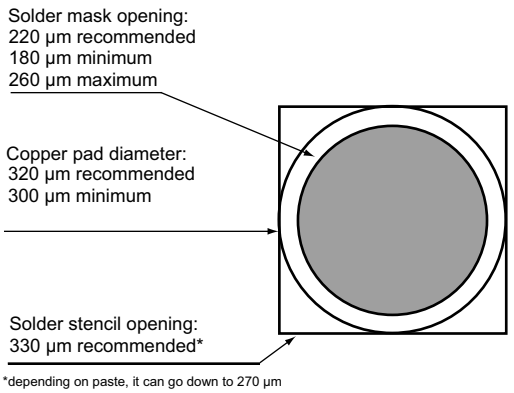


Figure 18. Footprint - 5 mils stencil - solder mask defined



3 Ordering information

Table 5. Ordering information

Order code	Marking	Weight	Base Qty	Delivery mode
BALF-NRF01D3	ST	1.82 mg	5000	Tape and Reel

4 Revision history

Table 6. Document revision history

Date	Revision	Changes
27-Mar-2014	1	Initial release
04-Jun-2014	2	Updated all curves and added *Table 4*.
25-Mar-2015	3	Updated cover page and *Table 2*, *Table 3* and *Table 4*.
07-Jul-2015	4	Updated *Table 1*.